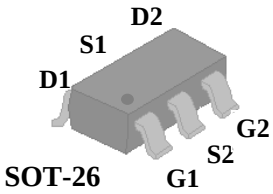
XP2531GY

Halogen-Free Product

N AND P-CHANNEL ENHANCEMENT MODE POWER MOSFET

- **Capable of 1.8V Gate Drive**
- **Lower Gate Charge**
- **Surface Mount Package**
- **RoHS Compliant & Halogen-Free**

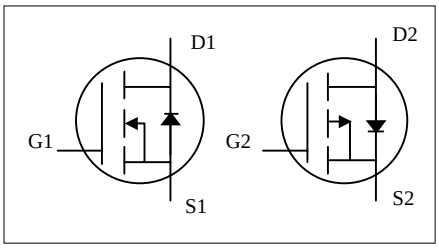


N-CH	BV_{DSS}	16V
	$R_{DS(ON)}$	58mΩ
	I_D	3.5A
P-CH	BV_{DSS}	-16V
	$R_{DS(ON)}$	125mΩ
	I_D	-2.5A

Description

XP2531 series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The SOT-26 package is widely used for all commercial-industrial applications.



Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating		Units
		N-channel	P-channel	
V_{DS}	Drain-Source Voltage	16	-16	V
V_{GS}	Gate-Source Voltage	±8	±8	V
I_D@T_A=25℃	Drain Current[3] , V_{GS} @ 4.5V	3.5	-2.5	A
I_D@T_A=70℃	Drain Current[3] , V_{GS} @ 4.5V	2.8	-2	A
I_{DM}	Pulsed Drain Current[1]	10	-10	A
P_D@T_A=25℃	Total Power Dissipation	1.14		W
T_{STG}	Storage Temperature Range	-55 to 150		℃
T_J	Operating Junction Temperature Range	-55 to 150		℃

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient[3]	110	℃/W

N-CH Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	16	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=4.5V, I_D=3A	-	-	58	mΩ
		V_{GS}=2.5V, I_D=2A	-	-	70	mΩ
		V_{GS}=1.8V, I_D=1A	-	-	85	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	0.2	-	1	V
g_{fs}	Forward Transconductance	V_{DS}=5V, I_D=3A	-	9	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=16V, V_{GS}=0V	-	-	10	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±8V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=3A	-	7	12	nC
Q_{gs}	Gate-Source Charge	V_{DS}=10V	-	0.6	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=4.5V	-	2	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=10V	-	6	-	ns
t_r	Rise Time	I_D=1A	-	11	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=3.3Ω	-	17	-	ns
t_f	Fall Time	V_{GS}=5V	-	3	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	365	585	pF
C_{oss}	Output Capacitance	V_{DS}=10V	-	70	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	60	-	pF
R_g	Gate Resistance	f=1.0MHz	-	1.5	3	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=0.9A, V_{GS}=0V	-	-	1.3	V

P-CH Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=-250uA	-16	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-4.5V, I_D=-2A	-	-	125	mΩ
		V_{GS}=-2.5V, I_D=-1.6A	-	-	165	mΩ
		V_{GS}=-1.8V, I_D=-1A	-	-	210	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=-250uA	-0.2	-	-1	V
g_{fs}	Forward Transconductance	V_{DS}=-5V, I_D=-2A	-	5	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-16V, V_{GS}=0V	-	-	-10	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±8V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=-2A	-	6	10	nC
Q_{gs}	Gate-Source Charge	V_{DS}=-10V	-	0.8	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=-4.5V	-	2	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=-10V	-	7	-	ns
t_r	Rise Time	I_D=-1A	-	20	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=3.3Ω	-	23	-	ns
t_f	Fall Time	V_{GS}=-5V	-	24	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	380	610	pF
C_{oss}	Output Capacitance	V_{DS}=-10V	-	90	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	75	-	pF
R_g	Gate Resistance	f=1.0MHz	-	8	16	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Forward On Voltage[2]	I_S=-0.9A, V_{GS}=0V	-	-	-1.3	V

Notes:

1.Pulse width limited by Max. junction temperature.

2.Pulse test

3.Surface mounted on 1 in^2 copper pad of FR4 board, t≤5sec ; 180℃/W when mounted on min. copper pad.

N-Channel

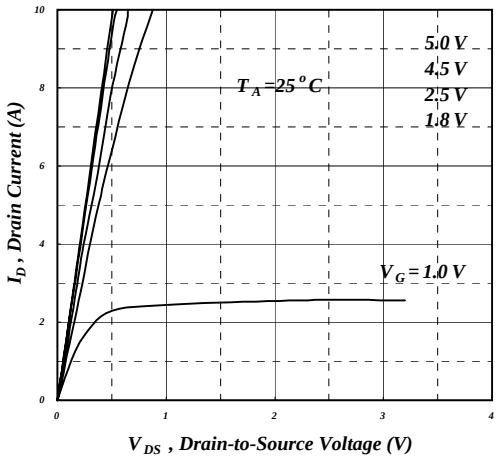


Fig 1. Typical Output Characteristics

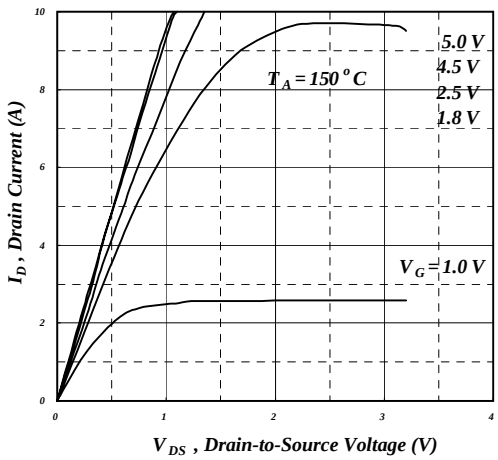


Fig 2. Typical Output Characteristics

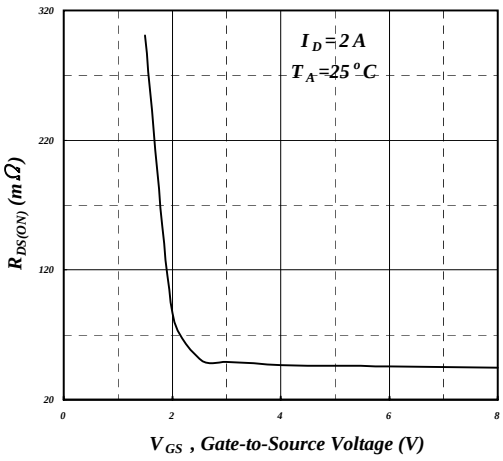


Fig 3. On-Resistance v.s. Gate Voltage

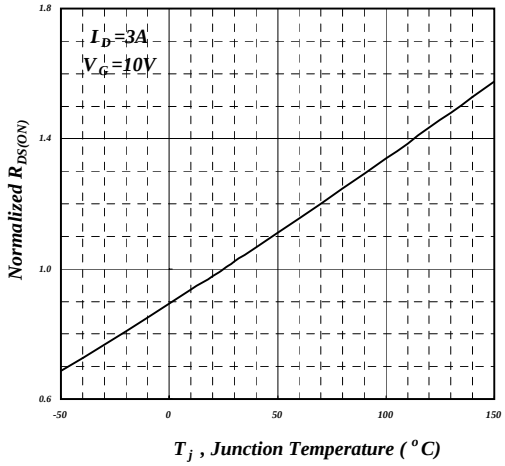


Fig 4. Normalized On-Resistance v.s. Junction Temperature

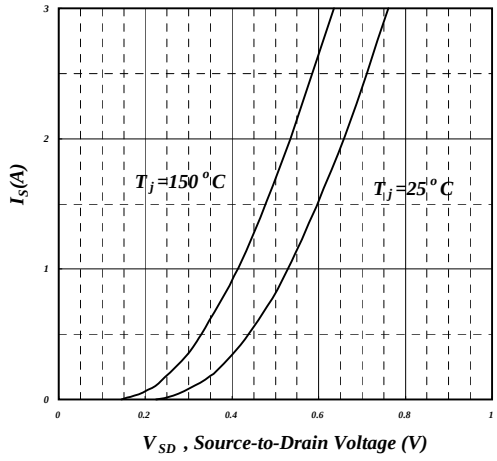


Fig 5. Forward Characteristic of Reverse Diode

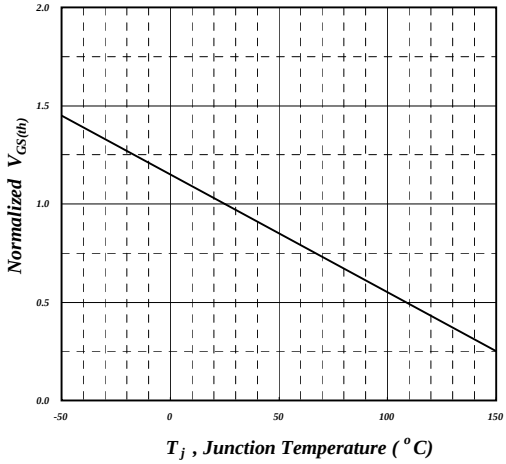


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

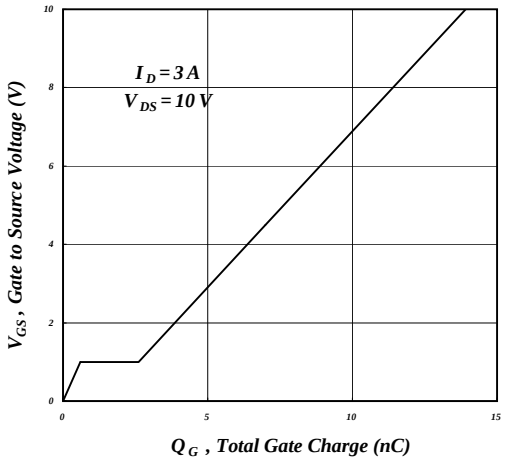


Fig 7. Gate Charge Characteristics

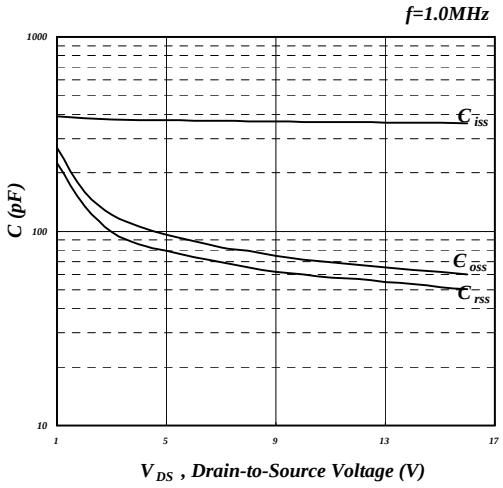


Fig 8. Typical Capacitance Characteristics

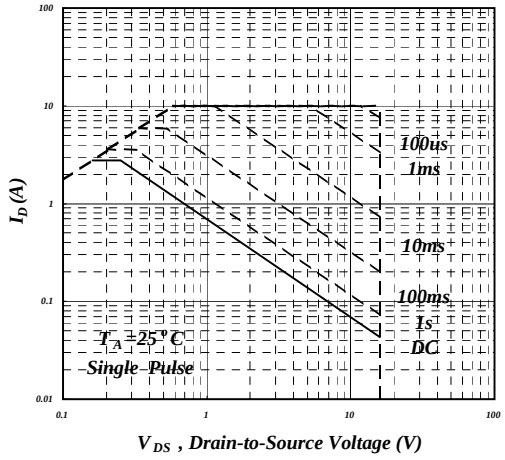


Fig 9. Maximum Safe Operating Area

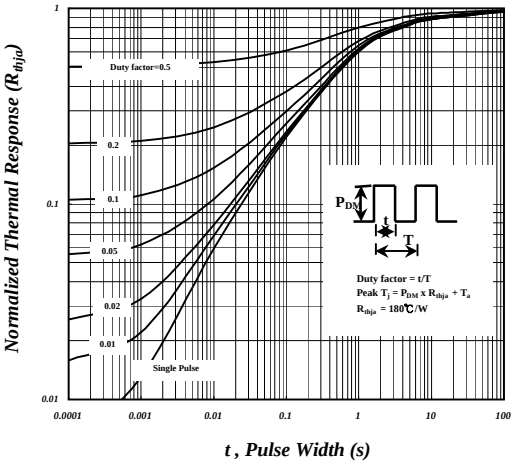


Fig 10. Effective Transient Thermal Impedance

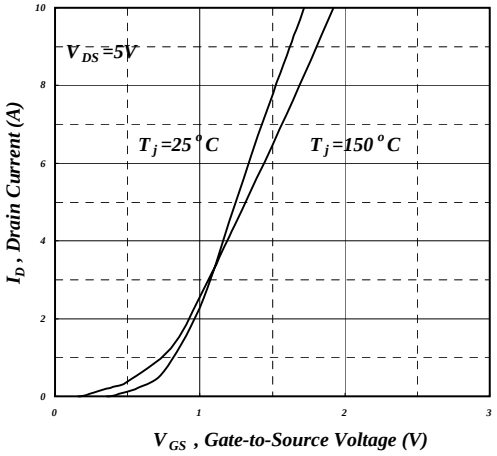


Fig 11. Transfer Characteristics

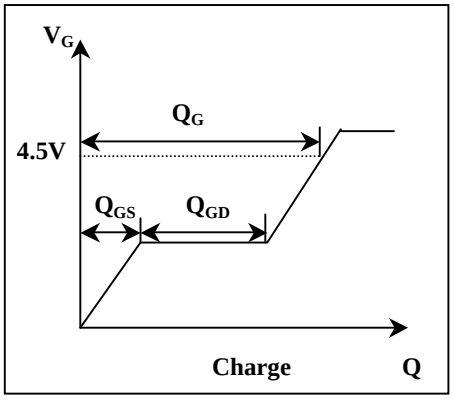


Fig 12. Gate Charge Waveform

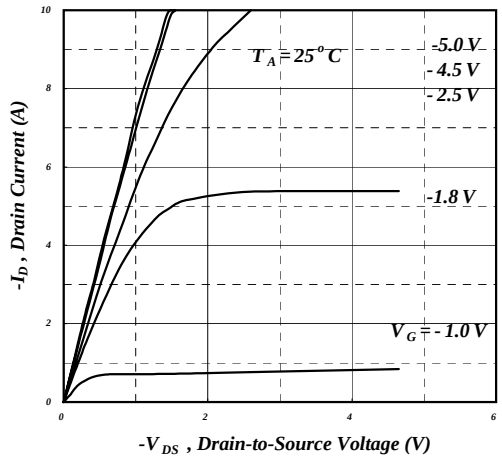


Fig 1. Typical Output Characteristics

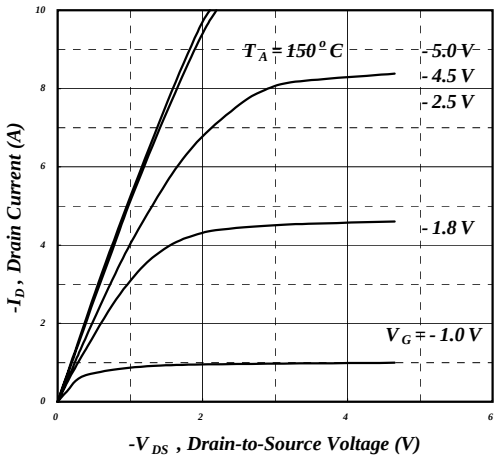


Fig 2. Typical Output Characteristics

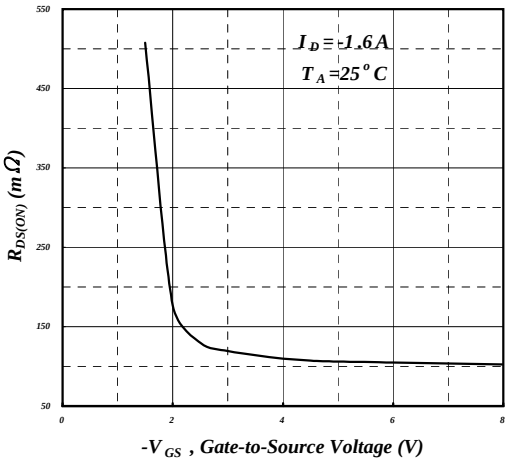


Fig 3. On-Resistance v.s. Gate Voltage

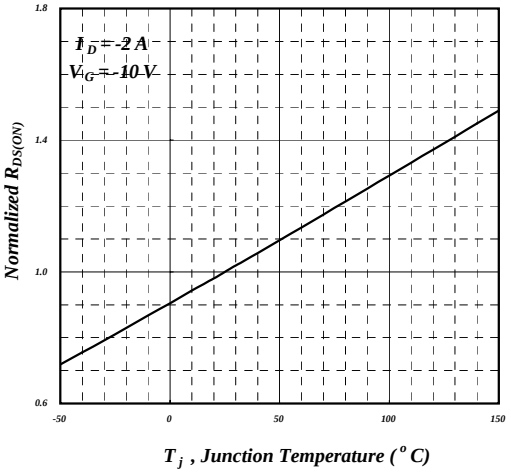


Fig 4. Normalized On-Resistance v.s. Junction Temperature

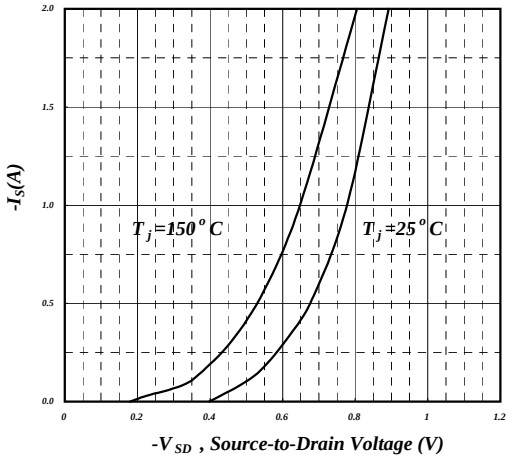


Fig 5. Forward Characteristic of Reverse Diode

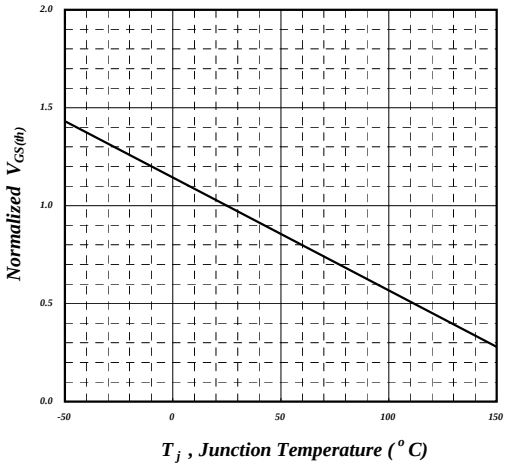


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

P-Channel

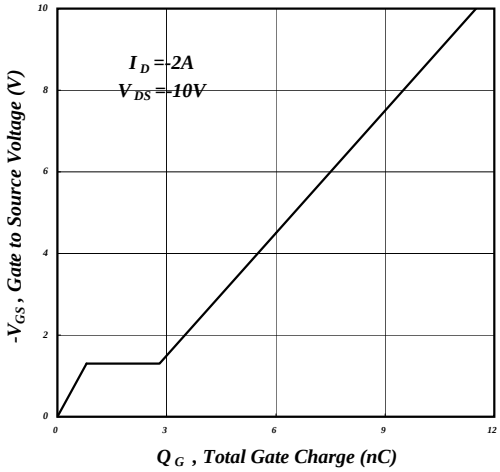


Fig 7. Gate Charge Characteristics

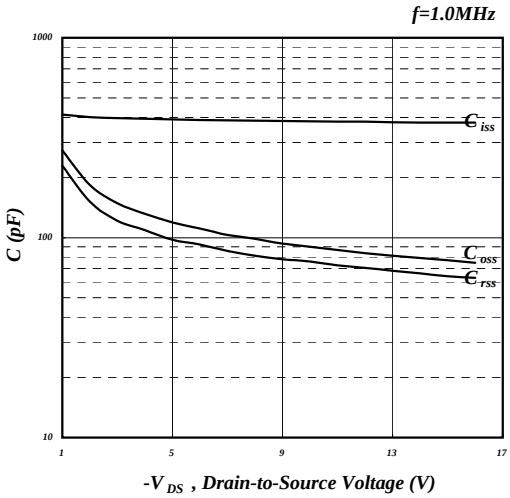
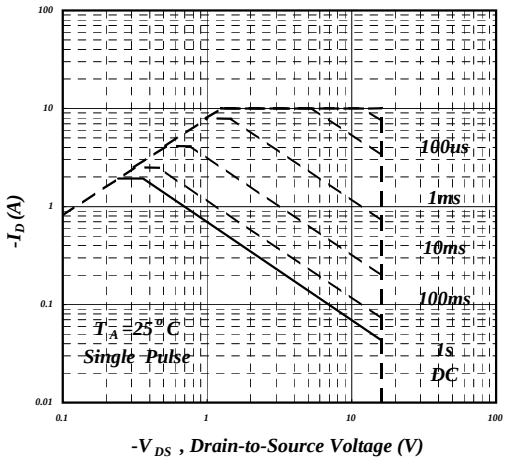


Fig 8. Typical Capacitance Characteristics



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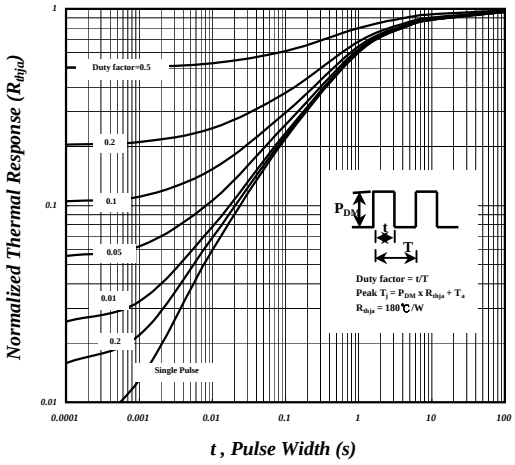

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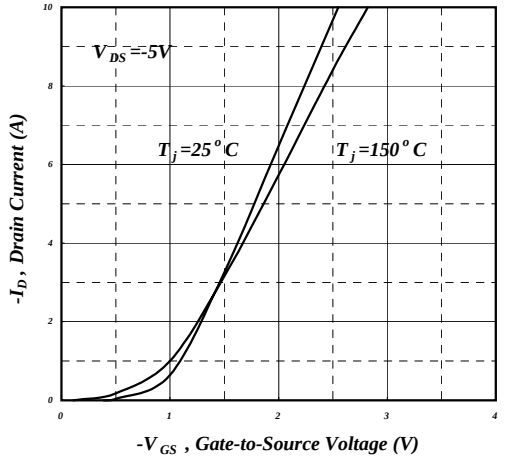


Fig 11. Transfer Characteristics

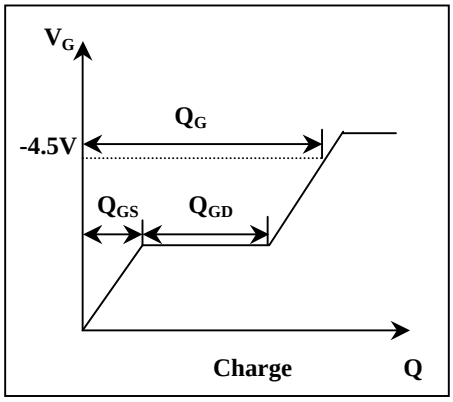
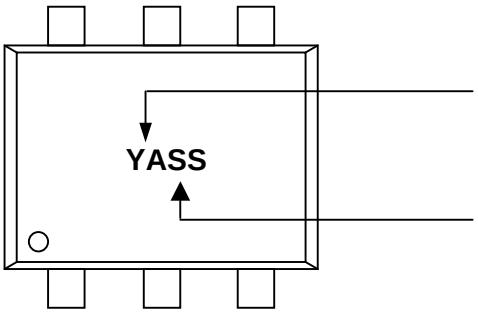


Fig 12. Gate Charge Waveform

MARKING INFORMATION



Part Number : YA

Date Code : SS

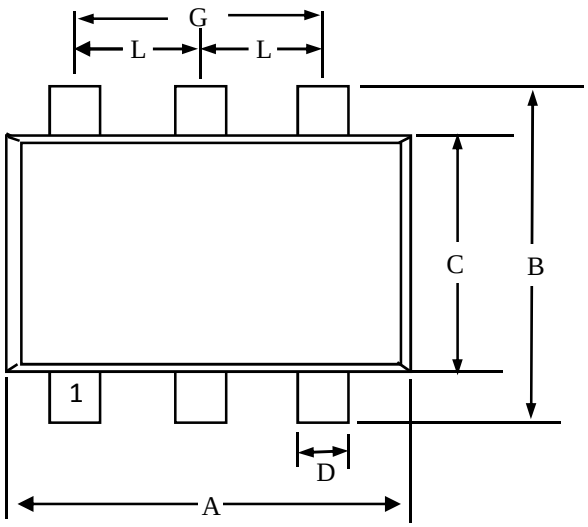
SS:2004,2008,2012,2016,2020,2024...

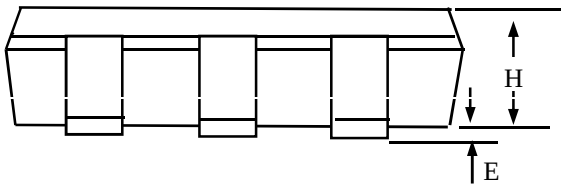
SS:2003,2007,2011,2015,2019,2023...

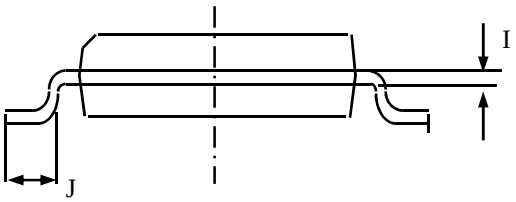
SS:2002,2006,2010,2014,2018,2022...

SS:2001,2005,2009,2013,2017,2021...

Package Outline : SOT-26







	Millimeters		
SYMBOLS	MIN	NOM	MAX
A	2.70	2.90	3.10
B	2.60	2.80	3.00
C	1.40	1.60	1.80
D	0.30	0.40	0.50
E	0.00	0.05	0.10
H	1.00	1.15	1.30
G	—	1.95 (ref.)	—
I	0.10	0.15	0.20
J	0.30	0.45	0.60
L	—	0.95 (ref.)	—

1.All Dimension Are In Millimeters.

2.Dimension Does Not Include Mold Protrusions.

Draw No. M1-Y6-G-v02

SOT-26 FOOTPRINT：